

What is claimed is:

1. A light emitting diode comprising:

a generally T-shaped body section including base portions having mounted surfaces for being mounted on a peripheral edge of a hole opened in a motherboard and an upright portion raised from said base portions for being inserted into said hole;

a resin forming section including a non-translucent frame projecting from a surface of said body section and an extension part which projects from said body section to project more forwardly than the frame and which has a mounted portion for being mounted on the peripheral edge of the hole of the motherboard;

a light emitting diode element mounted in a concave portion provided in said frame; and

a translucent sealing formed in said concave portion of the frame to seal said light emitting diode element.

2. The light emitting diode according to claim 1, wherein said resin forming section is formed integrally with said body section by a transfer forming.

3. The light emitting diode according to claim 1, wherein said mounted portion of the extension part is positioned to become the same level as the mounted surfaces of the base portions, and a suction portion is provided on a back surface of the mounted portion.

4. The light emitting diode according to claim 1, wherein said frame is provided with two mutually perpendicular light emitting planes.

5. The light emitting diode according to claim 1, wherein said frame is formed from a non-translucent resin of white color system.

6. The light emitting diode according to claim 1, wherein said body section is provided with a pair of substrate electrodes with which said light emitting diode is electrically connected.

7. A method for manufacturing a light emitting diode, comprising the steps of:

projecting and forming a resin forming section having a frame, on a front surface of a body section having an upright portion and base portions by a transfer forming;

providing a concave portion in the frame of the resin forming section;

disposing a light emitting diode element within the concave portion; and

filling a translucent resin in the concave portion to form a sealing body for sealing the light emitting diode.

8. A method for producing a light emitting diode, comprising the steps of:

forming a pair of electrodes on a body section having an upright portion and base portions;

projecting and forming a resin forming section having a frame and an extension part, on a surface of said body section by a transfer forming;

providing a concave portion in the frame of the resin forming section to expose a portion of one of the pair of electrodes;

disposing a light emitting diode element within the concave portion to conduct electrically with the one of the pair of electrodes; and

filling and hardening a translucent resin in the concave portion to form a sealing body for sealing the light emitting diode.